

RESIN DISPERSION EXCELLENT IN LOW-TEMPERATURE HEAT SEALING PROPERTY

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Abstract

PURPOSE: To obtain a resin dispersion excellent in low-temperature heat-sealing properties by using a modified PP powder obtained by evaporating a resin dispersion, prepared by dispersing a modified PP in a solid state in an organic solvent, to dryness at ordinary temperature so that the powder may have specified properties.

CONSTITUTION: A resin dispersion prepared by dispersing a modified PP at least partially graft-modified with an unsaturated carboxylic acid or its anhydride in a solid state in an organic solvent, wherein a modified PP powder obtained by evaporating this dispersion to dryness at ordinary temperature has the following properties A-D: (A) the melting point as measured by differential thermal analysis is 120-160 deg.C, (B) the degree of crystallinity as measured by X-ray diffractometry is 50-below 70%, (C) the intrinsic viscosity is 0.3-1.5dl/g, and (D) the content of the unsaturated carboxylic acid or its anhydride is 0.1-10wt%. This dispersion can be used as an adhesive for polyolefin and is excellent in low-temperature heat sealing properties.

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